[Causes/processes involved/keys to judgment]

A foreign object or a chemical residue remaining between plated copper surface and dry film prevents the adhesion of dry film, causing etching of conductor . Poor adhesion of dry film attributable to a bulge around a dent also causes the same defect. (Dry film lamination - etching process)



[コメント] 顕微鏡倍率× 10 [注釋] 显微镜倍率 × 10 [Coments] Magnification: ×10

1-2-1-5 円形打痕欠け/圆形压痕的缺口/ Round nick by dent

【特徴】欠けの淵に盛り上がりが見られ、裾が残っている欠け

【特征】边缘隆起、有锯齿状的缺口。

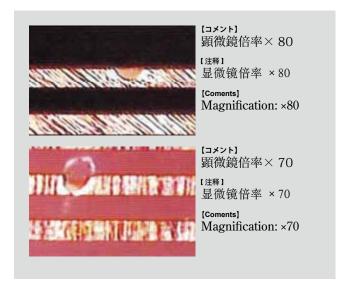
[Characteristics] There is a raised edge of a nick. The nick also has a tail.

【原因・判断ポイント・発生工程】基板銅めっき面の円形打痕の淵が盛り上がった為、DFRの密着が妨げられ、ET液に食われてできたもの(DFRラミネート \sim ET工程)

【原因、判断要点、发生工序】在板件的镀铜面有圆形压痕,其边缘隆起妨碍 DFR 的压合,被 ET 液腐蚀而发生的(DFR 压~ET 工序)。

[Causes/processes involved/keys to judgment]

The edge of a round dent on the plated copper surface of a base laminate is raised and prevents a close adhesion of dry film to cause etching of conductor. (Dry film lamination - etching process)



1-2-1-6 糊残り欠け/胶迹的缺口/ Nick by residual adhesive

【特徴】短絡や突起等と同居している複雑な欠け

【特征】短路和凸出等同时存在的复杂形状的缺口。

[Characteristics] A complicated nick together with shorts, spikes, etc.



[コメント] 顕微鏡倍率× 50 [注釋] 显微镜倍率 × 50 [Coments]

Magnification: ×50